

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10695187			
<b>Filing Date:</b>	28-Oct-2003			
<b>Title of Invention:</b>	Vertical removal of excess solder from a circuit substrate			
<b>First Named Inventor:</b>	William C. Weigler			
<b>Filer:</b>	Paul M. Hletko/David Hawkins			
<b>Attorney Docket Number:</b>	IS01207AP			
Filed as Large Entity				
<b>Utility Filing Fees</b>				
<b>Description</b>	<b>Fee Code</b>	<b>Quantity</b>	<b>Amount</b>	<b>Sub-Total in USD(\$)</b>
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
Notice of appeal	1401	1	500	500
<b>Post-Allowance-and-Post-Issuance:</b>				
<b>Extension-of-Time:</b>				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				<b>500</b>